



Fab and Wafer Sort Location Change for XQ18V04VQ44N Aerospace and Defense “XQ” Products

XCN10015 (v1.0) April 5, 2010

Product Change Notice

Overview

The purpose of this notification is to communicate a change in the wafer fabrication and sort facility for XQ18V04VQ44N flash memory configuration PROM device for Aerospace and Defense “XQ” products. There is no change to the fit or function of these devices. The form of these devices is changing with topside marking changes only.

Description

Production of XQ18V04VQ44N with the STMicroelectronics “T7Y” 150nm manufacturing process will transition from the STMicroelectronics M5 wafer fabrication facility in Catania, Italy to the Numonyx Fab2 wafer fabrication facility in Singapore (Table 1).

Table 1: Fabrication Facility Location Change Summary

Xilinx Family	Change Description
XQ18V04VQ44N	Wafer Fabrication and Sort Facility Changes from “M5” to “Fab2” Facility

This change will improve the ability of Xilinx to support this product effectively and to accommodate high-volume demand. There is no change in process technology associated with this notification. The same Numonyx T7Y 150nm manufacturing process is used at both the M5 and Fab2 facilities. The fit and function of devices manufactured at Fab2 and M5 facilities will be the same. The form of these devices is changing with topside marking change only. There is no change to the device IDCODE (the IDCODE revision for Fab2 has been changed to D for wafer fab identification purposes). Xilinx iMPACT software and recommended third party programming software will not be affected by this change.

Products Affected

This change affects XQ18V04VQ44N flash memory configuration PROM device for Aerospace and Defense “XQ” products.

Key Date and Cross Shipping Information for All Parts

No new production material is expected to be produced at the M5 facility. Upon availability of production units from the Fab2 facility, and no earlier than 90 days from the release date of this notice, customers may receive devices fabricated by either the Fab2 or M5 facilities until all inventory from the M5 facility is depleted.

Traceability

The topside marking will be changed from 'BRT' to 'BTT'. An example is shown in [Figure 1](#) below.

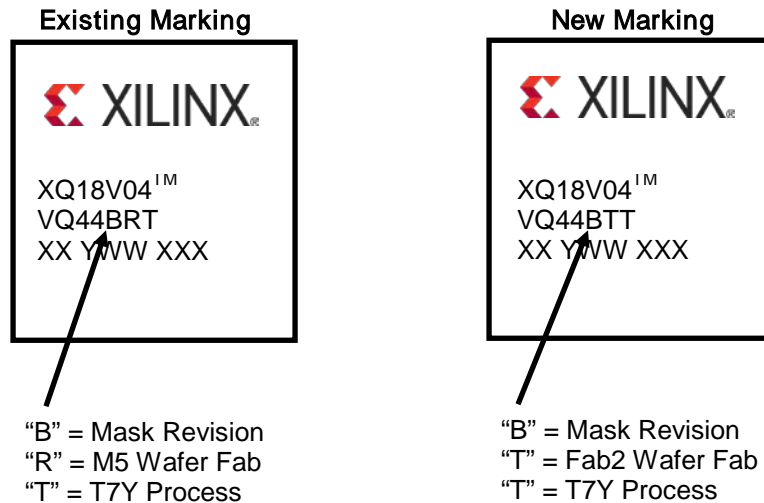


Figure 1: Sample Marking for Fabrication Change for XQ18V04 Device in VQ44 Package

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

Qualification Report (RPT142):
<https://secure.xilinx.com/webreg/clickthrough.do?cid=139884>

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/05/10	1.0	Initial release.

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